

Abstract

The present invention is aimed to provide an electroless gold plating solution which requires less amount of a reducing agent, retains a sufficient deposition rate for a practical use, and has an excellent stability as a plating solution; and a method for carrying out an electroless gold plating. The present invention provides an electroless gold plating solution comprising a gold salt, a phenyl compound based reducing agent and a water-soluble amine and a method for plating using the gold plating solution.



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